

UTAC Enhances North American Presence By Setting Up Package Design Center In Silicon Valley

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Center in Silicon Valley Complements the Package Development Center in Singapore HQ UTAC Also Looking into a Center in Europe

Singapore, May 22, 2002 - United Test and Assembly Center Limited ("UTAC"), a leader in semiconductor assembly and test services, today announces the setting up of a Package Design Center within UTAC America, Inc, its North American Headquarters in Pleasanton, California in the heart of Silicon Valley. The USA Package Design Center complements the existing Package Development Center in UTAC's Singapore headquarters.

The aim of UTAC America, Inc is to provide UTAC customers a complete service solution, in addition to manufacturing. It will focus on Sales, Package Design and Development. "We intend to grow UTAC by some 80% in Y2002, therefore requiring additional support for our US customer base", said Mr. JC Lee, UTAC's President & CEO. "We appointed Jack Snyder to our team as President, UTAC America Inc., to drive an aggressive marketing plan and Dr. Anthony Sun as Vice President of Advanced Packaging Development to expand our worldwide design and development centers".

"The Package Development/Design Centers will include core capabilities such as thermal, mechanical and electrical package analysis and package layout design for both leaded and laminate-based packages. In addition, we plan to embark on joint-development projects on advanced packages such as SiP, wCSP, FC-CSP, FC-BGA, multiple stacked-die CSP, to name a few with a strategic focus is Application Specific Package Design, especially for UTAC's recently unveiled Broadband, Mobile/Wireless (BM/W) blueprint.", said Dr Anthony Sun.

The BM/W strategy is UTAC's blueprint enhance its capabilities and service offering in this segment. This entails focusing its capital and human resources in chip-scale packaging, multi-chip modules, RF packages, high-speed digital testing, mixed-signal testing, RF testing, among others.

Mr Albert Ng, UTAC's Vice-President for Sales & Marketing added, "The setting up of our US Package Design Center will also enhance the timeliness of our technical service support to our US customers. For example, we expect to provide an expeditious design cycle, depending on the design complexity. We will looking into a similar infrastructure in Europe as part of our strategy of building a worldwide network of design, development & engineering centers."

About United Test and Assembly Center Ltd (UTAC)

United Test and Assembly Center Ltd. (UTAC), founded on 16th March 1998, is a QS9000/ISO9001/SAC certified semiconductor assembly and test services provider. We offer full turnkey services from wafer sort / laser repair, packaging, Test / Burn in, Mark-Scan-Pack and drop shipment services. In addition, we provide customers with value-added services in package design and simulation, test program development and device characterization, failure analysis services and full reliability test services.

UTAC is committed to provide customers one-stop turnkey semiconductor assembly and testing services for wide spectrum of memory, logic and mixed signal devices.

UTAC World Wide Web address is <http://www.utac.com.sg/>.